



[10191/3964]

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s) : Franz LAERMER et al.  
Serial No. : 10/530,612  
Filed : December 30, 2005  
For : **PLASMA SYSTEM AND METHOD FOR  
ANISOTROPICALLY ETCHING STRUCTURES  
INTO A SUBSTRATE**  
  
Art Unit : 1792  
Examiner : Maki A. Angadi  
Confirmation No. : 6739

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

Date: September 14, 2009

Signature:   
Richard M. Rosati (Reg. No. 31,792)

**RESPONSE**

SIR:

In response to a July 2, 2009 Office Action in the above-identified application, please reconsider the above-captioned application as follows.

**Remarks begin on page 2 of this paper.**